

Title (en)

Aluminum-alloy sputtering target and reflective film

Title (de)

Sputtertarget aus einer Aluminiumlegierung, und reflektierender Film.

Title (fr)

Cible de pulvérisation en alliage d'aluminium et film réflecteur.

Publication

**EP 1528119 B1 20070613 (EN)**

Application

**EP 04025435 A 20041026**

Priority

JP 2003370740 A 20031030

Abstract (en)

[origin: EP1528119A1] There are provided an aluminum-alloy reflection film for optical information-recording, having low thermal conductivity, low melting temperature, and high corrosion resistance, capable of coping with laser marking, an optical information-recording medium comprising the reflection film described, and an aluminum-alloy sputtering target for formation of the reflection film described. The invention includes (1) an aluminum-alloy reflection film for optical information-recording, containing an element Al as the main constituent, 1.0 to 10.0 at. % of at least one element selected from the group of rare earth elements, and 0.5 to 5.0 at. % of at least one element selected from the group consisting of elements Cr, Ta, Ti, Mo, V, W, Zr, Hf, Nb, and Ni, (2) an optical information-recording medium comprising any of the aluminum-alloy reflection films described as above, and (3) a sputtering target having the same composition as that for any of the aluminum-alloy reflection films described as above.

IPC 8 full level

**C23C 14/14** (2006.01); **C23C 14/34** (2006.01); **G11B 7/258** (2006.01); **G11B 11/00** (2006.01)

CPC (source: EP US)

**C23C 14/14** (2013.01 - EP US); **C23C 14/3414** (2013.01 - EP US); **G11B 7/258** (2013.01 - EP US); **G11B 7/2585** (2013.01 - EP US)

Cited by

CN113430422A; CN110951999A; US8512910B2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

**EP 1528119 A1 20050504**; **EP 1528119 B1 20070613**; AT E364737 T1 20070715; CN 100339900 C 20070926; CN 1612243 A 20050504; DE 602004006938 D1 20070726; DE 602004006938 T2 20080207; JP 2009087527 A 20090423; JP 4774094 B2 20110914; TW 200521964 A 20050701; TW I303056 B 20081111; US 2005112019 A1 20050526; US 2010202280 A1 20100812

DOCDB simple family (application)

**EP 04025435 A 20041026**; AT 04025435 T 20041026; CN 200410090068 A 20041101; DE 602004006938 T 20041026; JP 2008269836 A 20081020; TW 93132634 A 20041027; US 76732510 A 20100426; US 97114204 A 20041025